

此为证书 CN22/00003180.04 译本



长电科技（滁州）有限公司

中国安徽省滁州市世纪大道 999 号

依据主证书 CN22/00003180 中规定的管理体系已经过审核，并被证明符合下述要求
ISO 22301:2019

所涉及的活动范围覆盖
半导体元件封装的设计及半导体元件的封装和测试。

该证书的有效性自 2022 年 09 月 13 日 至 2025 年 09 月 12 日 并须经过符合要求的监督审核保持有效

版本号 1.
此证书的有效性取决于主证书的有效性。

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Certificate CN22/00003180.04

SGS

JCET Semiconductor (Chuzhou) Co., Ltd.

No.999, Shiji Road, Chuzhou City, Anhui Province, P.R.China

Has been assessed under the management system of the certified organisation defined in the main certificate CN22/00003180 as meeting the requirements of

ISO 22301:2019

For the following activities

Package design and assembly and testing of semiconductor devices.

This certificate is valid from 13 September 2022 until 12 September 2025 and remains valid subject to satisfactory surveillance audits.

Issue 1.

The validity of this certificate depends on the validity of the main certificate.

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